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(54) FLOW PATH MODULE, COOLANT DISTRIBUTION DEVICE, AND SERVER

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ABSTRACT (57)

A flow path module, adapted to a heat exchange element and a coolant and including a pipeline structure and at least one flow resistance element, is provided. The pipeline structure is adapted to be connected to the heat exchange element. The flow resistance element is disposed in the pipeline structure, and the coolant flows through the heat exchange element from the pipeline structure. A flow resistance of the flow resistance element is adapted to be adjusted corresponding to a flow resistance of the heat exchange element. A coolant distribution device and a server are also provided.

